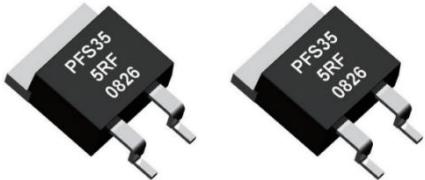


TFS35 Series

TO220 High Power Thick Film SMD Resistors



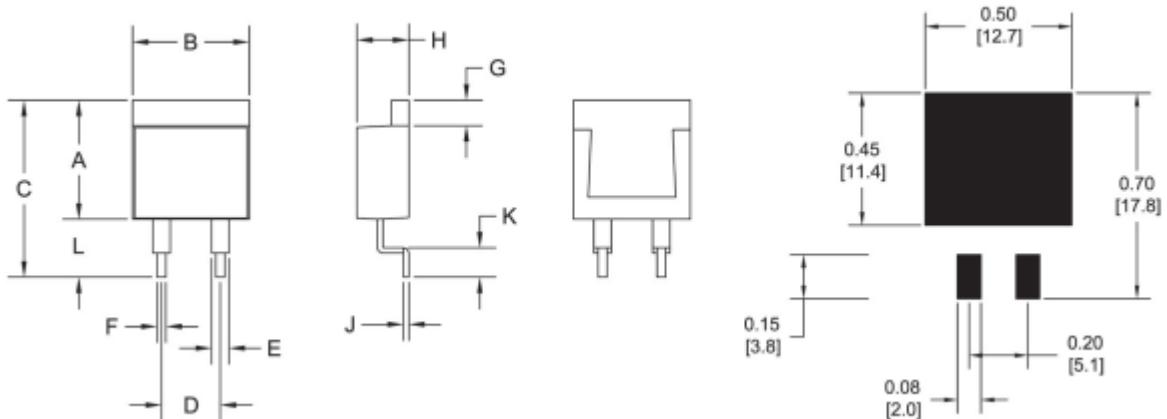
- D2PAK Housing
- Resistances From 0.01Ohm to 500kOhms
- 35 Watts At 25°C Case Temperature On Heat Sink
- Resistance Tolerances to $\pm 1\%$
- TCR to $\pm 50\text{ppm}/^\circ\text{C}$
- Load Stability to 1%
- Low Ohm Values For Current Sense Applications
- Exceptional Pulse Performance
- Solder Reflow Secure At 250°C / 30s
- Electrically Isolated From Back Plate
- Low Inductance - 0.1 μH Maximum
- RoHS Compliant
- Flammability UL94V-0

■ SPECIFICATIONS

Type	TFS35				
Terminals	2				
Terminal Finish	Tin Plated Copper				
Power Rating (with heat sink)	35 W (2W on Simple solder Pad)				
Thermal Resistance R _{thj-c}	3.4 °C/W				
Resistance Range	0.01 to 0.099Ohms	0.1 to 9.90Ohms	10 to 100KOhms		
Tolerances (others upon request)	5%	1% / 5%	1%		
Temperature Coefficient	$\pm 250 \text{ ppm}/^\circ\text{C}$	$\pm 100 \text{ ppm}/^\circ\text{C}$	$\pm 50 \text{ ppm}/^\circ\text{C}$		
Operating Temperature	-55°C to 175°C				
Max Operating Voltage	500VDC				
Inductance	0.1uH				
Voltage Proof	2.0kVDC				
Insulation Resistance	Over 4,000 Mega ohm				
Dielectric strength	2,000VDC				
Load Life	$\pm 1\%$	90 min ON, 30 min OFF, 1000hrs @ 25°C			
Humidity	$\pm 1\%$	90-95% RH, 0.1W, 1000 hrs @ 40°C			
Temperature Cycle	$\pm 0.25\%$	-55°C for 30 min, $+155^\circ\text{C}$ for 30 min, 5cycles			
Solder Heat	$\pm 0.1\%$	$350^\circ\text{C} \pm 5^\circ\text{C}$ for 3 seconds			
Vibration	$\pm 0.25\%$	5G 10~2Khz 20min / 12cycles			
Flammability	UL94V-0				
Reflow soldering	250°C / 30s / 3cycles (sufficient cooling between each cycles)				
Moisture Sensitivity Level	MSL-1				
Mass	1.5g				

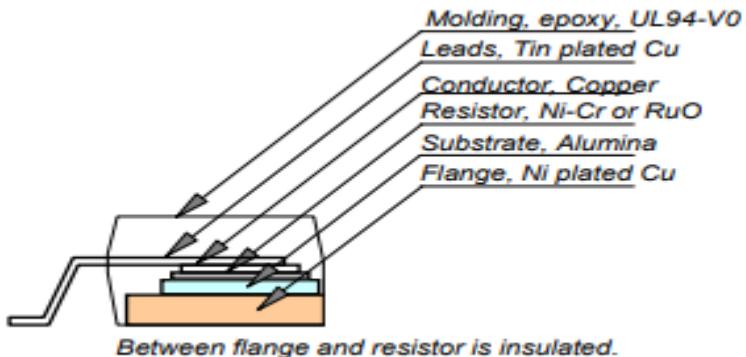
DIMENSIONS

Back plate is isolated from both pins.



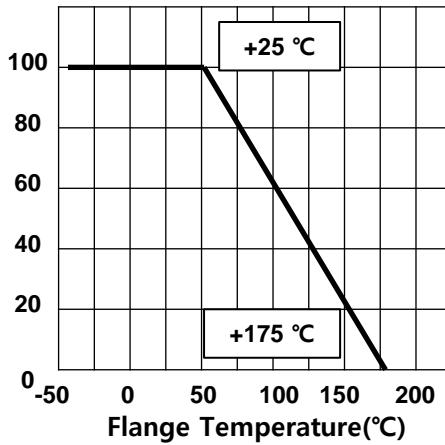
Dimension	mm	Tol (±mm)	inches	Tol (±inches)
A	10.3	0.2	0.405	0.008
B	10.1	0.2	0.400	0.008
C	15.3	1.2	0.602	0.047
D	5.08	0.1	0.200	0.004
E	1.5	0.05	0.060	0.002
F	0.75	0.05	0.030	0.002
G	2.2	0.2	0.087	0.008
H	4.5	0.2	0.177	0.008
J	0.5	0.05	0.020	0.002
K	2.5	0.5	0.10	0.02
L	5.0	1.0	0.20	0.04

Structure and Materials



□ DERATING CURVES

% Power



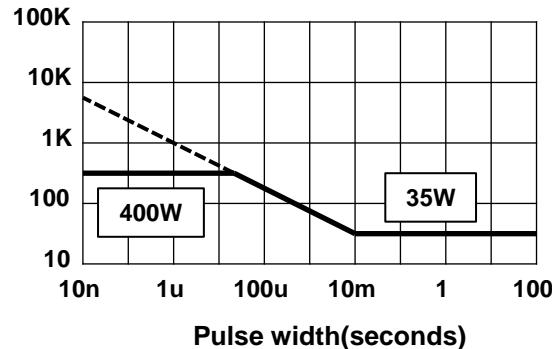
Power Rating Notes-

The TFS35 Series Resistors must be attached to a suitable heatsink.
The maximum internal resistor temperature is 175°C
To specify an appropriate heatsink use the following formula

$$R_{\text{eff}} = \frac{T_{\text{MAX}} - (P * R_{\text{eff}}) - T_{\text{A}}}{P}$$

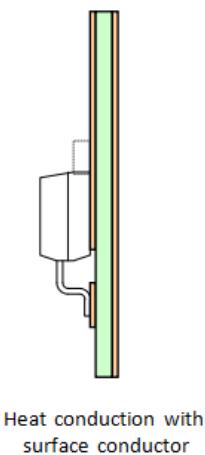
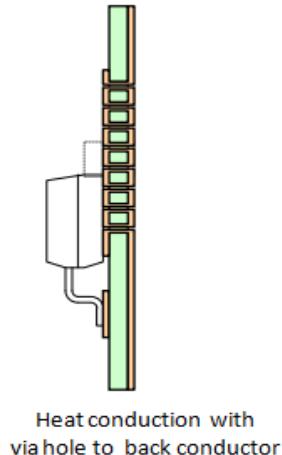
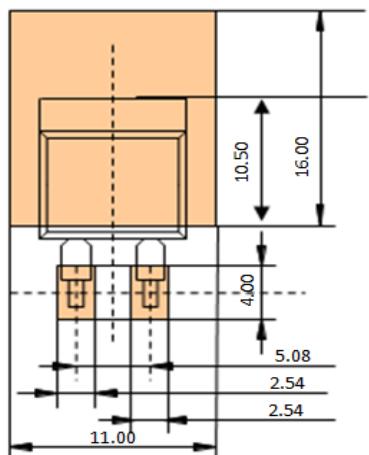
Where:
 R_{IH} = Thermal Resistance of Heatsink (K/W)
 R_{IR} = Thermal Resistance of Resistor (K/W)
 T_{MAX} = Maximum Temperature of Resistor
 T_{A} = Ambient Temperature of Heatsink (°C)
 P = Power Through Resistor (W)

Pulse Peak Power(W)

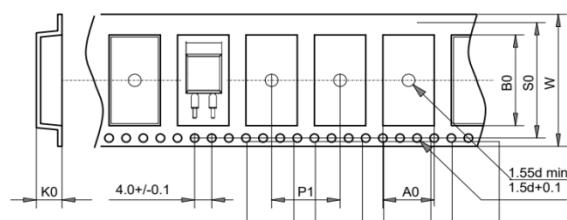


Tentative continuous-pulse allowance at duty 0.01. Load life test will be necessary in actual equipment, because curve may be changed by resistance, repetition, duty and operating temperature

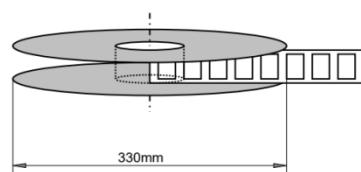
Applications .TFS35



Tape Reel ,TPFS35 (500pcs/reel)

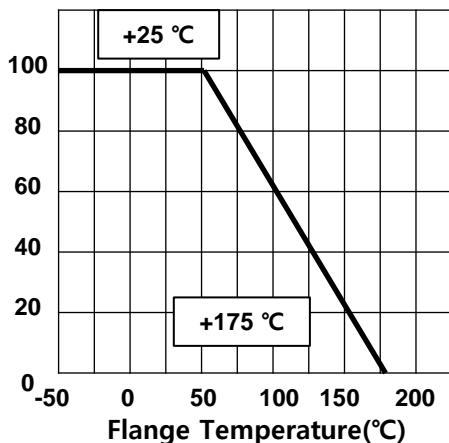


A0	12+/-0.3
B0	16+/-0.3
K0	6.1+/-0.3
P1	16+/-0.3
S0	20+/-0.3
W	24+/-0.3



□ DERATING CURVES

% Power



Power Rating Notes-

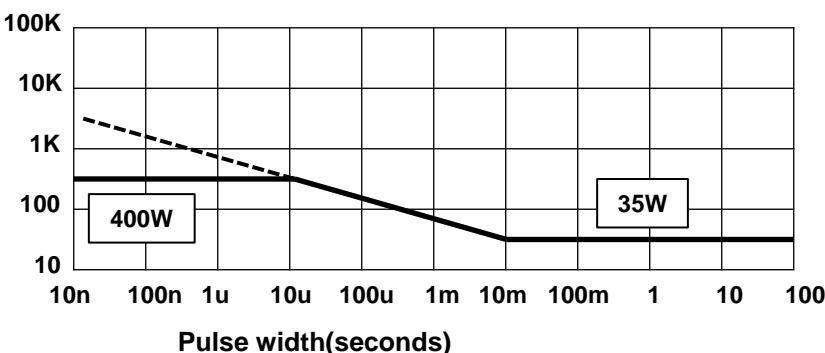
The TFS35 Series Resistors must be attached to a suitable heatsink.
The maximum internal resistor temperature is 175°C
To specify an appropriate heatsink use the following formula

$$R_{\text{eff}} = \frac{T_{\text{MAX}} - (P * R_{\theta R}) - T_A}{P}$$

Where:

R_{IH} = Thermal Resistance of Heatsink (K/W)
 $R_{\theta R}$ = Thermal Resistance of Resistor (K/W)
 T_{MAX} = Maximum Temperature of Resistor
 T_A = Ambient Temperature of Heatsink (°C)
 P = Power Through Resistor (W)

Pulse Peak Power(W)



Tentative continuous-pulse allowance at duty 0.01. Load life test will be necessary in actual equipment, because curve may be changed by resistance, repetition, duty and operating temperature

□ HOW TO ORDER

TFS35	10KΩ	±1%	NOTE
TYPE	RESISTANCE	TOLERANCE ±1% ±5%	TAPE 500Pcs Packaging